

REMARKS

The specification has been amended to identify information relating to the international application and priority application of the present application.

Claims 1 to 7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Akita et al. (WO 01/62517 based on the disclosure of corresponding publication U.S. Patent No. 6,779,733; hereinafter "Akita") in view of Higuchi et al. (U.S. Patent No. 6,380,614; hereinafter "Higuchi").

The Office states that Akita discloses the limitations of the non-contact ID card and method of manufacturing a non-contact ID card of the present application except for the feature that a thermoplastic resin is used for the enlarged electrode. The Office cites Higuchi as teaching a non-contact IC card manufacturing system including the coating of an insulating resin with a thermoplastic resin. The position of the Office is that it would have been obvious to one of ordinary skill in the art to incorporate the teachings of Higuchi into Akita in order to improve IC card components by using a thermoplastic resin.

Applicants respectfully submit that the combination of Akita and Higuchi fails to support a *prima facie* case of obviousness of the claims of the present application under 35 U.S.C. § 103(a).

The invention of Akita is described in the background portion of the present application. In the non-contact ID card of Akita, a metal electrode of an antenna and an enlarged metal electrode of an interposer board are joined by the use of a conductive adhesive material. Akita does not disclose or suggest forming the enlarged electrode of a conductive resin containing a thermoplastic resin (and eliminating the conductive adhesive material).

Higuchi does not overcome the deficiencies of Akita and appears to be mischaracterized by the Office.

Higuchi merely describes using a thermoplastic resin as a coating for intensifying lamination of a non-contact IC card. In Higuchi a non-contact IC card is formed by coating a laminate together with a semiconductor element (54) and an antenna coil (plane coil, 52) of the IC card with a thermoplastic resin (74). The thermoplastic resin of Higuchi is not conductive and is not an electrode and Higuchi does not disclose and does not suggest using a thermoplastic resin in a non-contact IC card for electric conduction.

In view of the limitation in Higuchi to the use of a thermoplastic resin as a coating for intensifying lamination and in view of the lack of teachings in Higuchi concerning the use of a thermoplastic resin in a conductive resin, even if a person of ordinary skill in the art would have been motivated to combine Akita and Higuchi, the combination would not have resulted in the non-contact ID card of the present application in which an enlarged electrode is a resin electrode made of a conductive resin containing thermoplastic resin.

Removal of the 35 U.S.C. 103(a) rejection of the claims is believed to be in order and is respectfully requested.

The foregoing is believed to be a complete and proper response to the Office Action dated November 14, 2006, and is believed to place this application in condition for allowance. If, however, minor issues remain that can be resolved by means of a telephone interview, the Examiner is respectfully requested to contact the undersigned attorney at the telephone number indicated below.

In the event that this paper is not considered to be timely filed, applicants hereby petition for an appropriate extension of time. The fee for any such extension may be charged to our Deposit Account No. 111833.

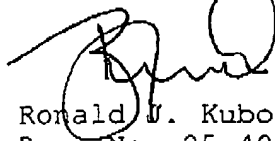
PATENT APPLN. NO. 10/532,087  
RESPONSE UNDER 37 C.F.R. §1.111

**PATENT  
NON-FINAL**

In the event any additional fees are required, please also  
charge our Deposit Account No. 111833.

Respectfully submitted,

KUBOVCIK & KUBOVCIK



Ronald W. Kubovcik  
Reg. No. 25,401

Atty. Case No. OGA-014  
The Farragut Building  
Suite 710  
900 17th Street, N.W.  
Washington, D.C. 20006  
Tel: (202) 887-9023  
Fax: (202) 887-9093  
RJK/jbf